

Variant: 001

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TID #: 'TIDM-CAPTIVATE-REMOTECONTROL



TIDM-CAPTIVATE-REMOTECONTROL REV 1_0 Bill of Materials

Item #	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package Reference
1	C1, C6	2	0.1uF	C1005X5R1A104K	TDK	CAP, CERM, 0.1 μ F, 10 V, +/- 10%, X5R, 0402, CAP, CERM, 0.1uF, 10V, +/-10%, X5R, 0402	0402
2	C2, C5	2	1uF	C1608X5R1A105K	TDK	CAP, CERM, 1 μ F, 10 V, +/- 10%, X5R, 0603	0603
3	C3, C4	2	12pF	GRM1555C1E120JA01D	MuRata	CAP, CERM, 12 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
4	C7	1	100uF	C1206C107M9PACTU	Kemet	CAP, CERM, 100 μ F, 6.3 V, +/- 20%, X5R, 1206_190	1206_190
5	C8	1	1000pF	C1005X7R1H102K	TDK	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0402	0402
6	C9	1	10uF	C0805C106K8PACTU	Kemet	CAP, CERM, 10 μ F, 10 V, +/- 10%, X5R, 0805	0805
7	D1	2	Green	LTST-C190GKT	Lite-On	LED, Green, SMD	1.6x0.8x0.8mm
8	D2	2	Red	LTST-C190CKT	Lite-On	LED, Red, SMD	1.6x0.8x0.8mm
9	J6, J30, J32	3		TSW-107-07-G-S	Samtec	Header, 100mil, 7x1, Gold, TH	7x1 Header
10	R1, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19	14	470	CRCW0402470RJNED	Vishay-Dale	RES, 470, 5%, 0.063 W, 0402	0402
11	R2, R3	2	390	CRCW0402390RJNED	Vishay-Dale	RES, 390, 5%, 0.063 W, 0402	0402
12	R4, R5	2	2.2k	CRCW04022K20JNED	Vishay-Dale	RES, 2.2 k, 5%, 0.063 W, 0402	0402
13	R6	1	47k	CRCW040247K0JNED	Vishay-Dale	RES, 47 k, 5%, 0.063 W, 0402	0402
14	R20, R21	2	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402
15	RF1, RF2	2		TFM-110-02-S-D-A-K-TR	Samtec	CONN SHRD HDR HDR 20 POS 1.27MM SLDR ST SMD	15.88x6.35x5.72mm
16	U1	1		DRV2605LDGS	Texas Instrumen	Haptic Driver for LRA and ERM With Built-In Library and Smart Loop Architecture, DGS0010A	DGS0010A
17	U2	1		MSP430FR2633IRHB	Texas Instrumen	MSP430 Captivate Microcontroller	RHB (32VQFN)
18	Y1	1		MS3V-T1R 32.768KHZ +/-20PPM 12.5PF	Micro Crystal AG	Crystal, 32.768kHz, 12.5pF, SMD	1.4x1.4x5.0mm SMD

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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